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(54) Title: MULTI-LAYER CIRCUIT ASSEMBLY AND PROCESS FOR PREPARING THE SAME

(57) Abstract: Processes for fabricating a multi-layer circuit assembly and a multi-layer circuit assembly fabricated by such processes are provided. The process includes (a) providing a substrate at least one area of which comprises a plurality of vias, these area(s) having a via density of 500 to 10,000 holes/square inch (75 to 1550 holes/square centimeter); (b) applying a dielectric coating onto all exposed surfaces of the substrate to form a conformal coating thereon; and (c) applying a layer of metal to all surfaces of the substrate. Additional processing steps such as circuitization may be included.



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